AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): An electronic part device comprising a semiconductor circuit substrate, a semiconductor element mounted thereon in such a way that an electrode part for connection disposed on the semiconductor element and an electrode part for connection disposed on the circuit substrate are facing with each other, and a filling resin layer which fills ~~the~~ a gap between the circuit substrate and semiconductor element, wherein the filling resin layer comprises a liquid epoxy resin composition which comprises the following component (D) and the following components (A) to (C):

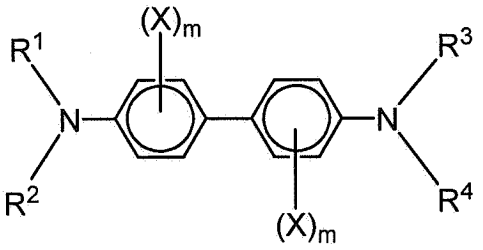
(A) a liquid epoxy resin,

(B) a curing agent,

(C) an N,N,N',N'-tetra-substituted fluorine-containing aromatic diamine compound, and

(D) a carboxylic acid vinyl ether addition product.

2. (original): The electronic part device described in claim 1, wherein the aforementioned N,N,N',N'-tetra-substituted fluorine-containing aromatic diamine compound as the component (C) is a compound represented by the following general formula (1):



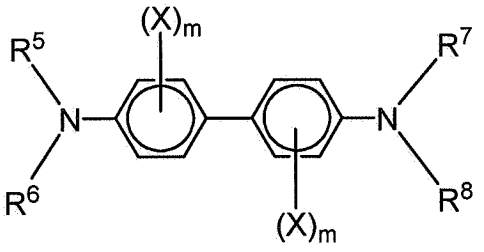
... (1)

(in the formula (1), X is fluorine and/or C_nF_{2n+1} (n is a positive number of from 1 to 10), m is an integer of from 1 to 4, and R^1 to R^4 are monovalent organic groups other than hydrogen, which may be the same or different from one another).

3. (currently amended): The electronic part device described in claim 1 ~~or 2~~, wherein the N,N,N′,N′-tetra-substituted fluorine-containing aromatic diamine compound as the component (C) is a reaction product of 2,2′-di(trifluoromethyl)-4,4′-diaminobiphenyl with a mono-epoxy compound containing one epoxy group in one molecule.

4. (currently amended): The electronic part device described in ~~any one of claims 1 to 3~~claim 1, wherein the content of the N,N,N′,N′-tetra-substituted fluorine-containing aromatic diamine compound as the component (C) is set to a range of from 10 to 70% by weight, more preferably from 20 to 40% by weight, based on the entire organic components of the liquid epoxy resin composition.

5. (currently amended): The electronic part device described in ~~any one of claims 1 to 4~~claim 1, wherein the curing agent as the component (B) is at least one of the fluorine-containing aromatic diamine represented by the following general formula (2) and a derivative thereof:



... (2)

(in the formula (2), X is fluorine and/or C_nF_{2n+1} (n is a positive number of from 1 to 10), m is an integer of from 1 to 4, each of R^5 to R^8 is hydrogen or a monovalent organic group, and at least one of R^5 to R^8 is hydrogen).

6. (currently amended): The electronic part device described in ~~any one of claims 1 to 5~~claim 1, which comprises a prepolymer prepared by allowing at least one of the fluorine-containing aromatic diamine represented by the aforementioned general formula (2) and a derivative thereof to react with the liquid epoxy resin as the component (A).

7. (original): The electronic part device described in claim 3, wherein the mono-epoxy compound containing one epoxy group in one molecule is at least one compound selected from the group consisting of n-butyl glycidyl ether, allyl glycidyl ether, 2-ethylhexyl glycidyl ether, styrene oxide, phenyl glycidyl ether, cresyl glycidyl ether, lauryl glycidyl ether, p-sec-butylphenyl glycidyl ether, nonylphenyl glycidyl ether, glycidyl ether of carbinol, glycidyl methacrylate, vinylcyclohexene monoepoxide and α-pinene oxide.

8. (original): The electronic part device described in claim 1, wherein the carboxylic acid vinyl ether addition product as the component (D) is a carboxylic acid monovinyl ether addition product represented by the following general formula (3)

$$R^{10}\text{-}[CO\text{-}O\text{-}CH(CH_3)\text{-}O\text{-}R^{11}]_n \quad \cdots (3)$$

(in the formula (3), R^{10} is an organic group of monovalent or more, R^{11} is an organic group of monovalent or more, wherein they may be the same or different from each other, and n is a positive integer).

9. (original): The electronic part device described in claim 1, wherein the carboxylic acid vinyl ether addition product as the component (D) is a polyvalent carboxylic acid polyvalent vinyl ether addition product having a structural unit represented by the following general formula (4) as the main moiety

$$-[O\text{-}CO\text{-}R^{12}\text{-}CO\text{-}O\text{-}CH(CH_3)\text{-}O\text{-}R^{13}\text{-}O\text{-}CH(CH_3)]_n- \quad \cdots (4)$$

(in the formula (4), R^{12} and R^{13} are divalent organic groups, wherein they may be the same or different from each other, and n is a positive integer).

10. (currently amended): The electronic part device described in ~~any one of claims 1 to 9~~claim 1, which further comprises an inorganic filler in the liquid epoxy resin composition containing the components (A) to (D).

11. (original): The electronic part device described in claim 10, wherein the inorganic filler is a spherical silica powder having an average particle diameter of 10 μm or less.